AMENDMENT AND RESPONSE UNDER 37 C.F.R. § 1.111

Serial Number: 09/473,315

Filing Date: December 28, 1999

HIGH PERFORMANCE CAPACITOR

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IN THE CLAIMS

Please substitute the claims in the appendix entitled "Clean Version of Pending Claims" for the previously pending claims. Specific amendments to individual claims are detailed in the following marked up claims.

Please amend the claims as follows:

- 4. (Amended) The capacitor of claim 1, wherein the plurality of [controlled collapse chip] connection sites have a pitch of between about 100 and about 500 microns.
- 6. (Amended) A capacitor comprising:

a plurality of first conductive layers, each of the plurality of first conductive layers formed on a first dielectric sheet;

a plurality of second conductive layers, each of the plurality of second conductive layers formed on a second dielectric sheet, and the plurality of second conductive layers interlaced with the plurality of first conductive layers;

a pair of dielectric sheets, each of the pair of dielectric sheets having a thickness slightly greater than about 7 microns, for providing a pair of substantially rigid outer surfaces for the plurality of second conductive layers interlaced with the plurality of first conductive layers, each of the pair of substantially rigid outer surfaces having [a number of surfaces having] a plurality of connection sites operable for coupling the capacitor to a substrate using a controlled collapse chip connection (C4); and

a plurality of vias coupling the plurality of first conductive layers and the plurality of second conductive layers to at least two of the plurality of connection sites.

9. (Amended) A capacitor comprising:

a multilayered capacitor having a <u>pair of substantially rigid</u> [number of] outer surfaces; and

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a plurality [a number] of pads located on the pair of substantially rigid [at least two of the imber of] outer surfaces wherein at least two of the plurality [number] of pads are capable of being coupled to a substrate using a solder bump.

Cancel claim 17 without prejudice.

REMARKS

Applicant has reviewed and considered the Office Action mailed on March 7, 2001 and the references cited therewith.

The proposed amendment to the drawings is made to clarify the disclosure in accordance with the objections made on page 2 of the Office Action. A copy of originally-filed Figure 5, showing the proposed amendment in red ink, is attached hereto.

The amendment to the specification is made to ensure correspondence between the drawings and the specification.

Claims 4, 6 and 9 are amended, claim 17 is cancelled, claims 13-16 and 18-29 were previously canceled without prejudice, and no claims are added; as a result, claims 1-12 are now pending in the application.

Rejections Under 35 U.S.C.§112

Claim 4 was rejected under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. Applicant has amended claim 4 to ensure correct antecedent basis for all terms in the claim. Applicant requests withdrawal of the rejection and reconsideration and allowance of claim 4.

Rejections Under 35 U.S.C.§102

Claims 1 and 4-5 were rejected under 35 U.S.C.§102(e) as being anticipated by Herrell et al. (U.S. Patent No. 6,191,479). Applicant traverses the rejections.

Applicant does not admit that Herrell et al. is prior art and reserves the right to swear behind Herrell et al. as provided for under 37 C.F.R. 1.131.